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SPECIFICATION



- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31A475KACLNNC
- Descriptiont : CAP, 4.7 µF, 25V, ±10%, X5R, 1206

		<u>CL</u>	<u>31</u>	<u>A</u>	<u>475</u>	<u>K</u>	<u>A</u>	<u>C</u>	Ŀ	N	<u>N</u>	<u>C</u>		
		1	2	3	4	5	6	1	8	9	10	1		
1	Series	Samsung Mu	lti-laye	r Cer	amic (Сара	citor							
2	Size	1206 (inch	code)		L:	3.2	± 0.2	2	mm		W:	1.6	± 0.2	mm
						8	Thic	knes	ss div	/isio	n	Low p	orofile	
3	Dielectric	X5R					Inne	r ele	ctroc	le		Ni		
4	Capacitance	4.7 μF					Tern	ninat	tion			Cu		
5	Capacitance	±10 %					Plati	ng				Sn 10	0%	(Pb Free)
	tolerance					9	Proc	luct				Norm	al	
6	Rated Voltage	25 V				10	Spee	cial				Rese	rved for	future use
\bigcirc	Thickness	0.85 ± 0.1	mm			1	Pack	cagir	ng			Cardb	board T	ype, 7"reel(4,000ea)

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition							
Capacitance	Within specified tolerance	1ktz±10% 1.0±0.2Vrms							
Tan δ (DF)	0.1 max.								
Insulation	More than 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.							
Resistance									
Appearance	No abnormal exterior appearance	Visual inspection							
Withstanding	No dielectric breakdown or	250% of the rated voltage							
Voltage	mechanical breakdown								
Temperature	X5R								
Characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)								
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.							
of Termination	terminal electrode								
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)							
		with 1.0mm/sec.							
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder							
	is to be soldered newly	245±5℃, 3±0.3sec.							
		(preheating : 80~120 ℃ for 10~30sec.)							
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.							
Soldering heat	Tan δ, IR : initial spec.								

	Performance	Test condition						
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm						
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)						
		2hours \times 3 direction (x, y, z)						
Moisture	Capacitance change : within ±12.5%	With rated voltage						
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500 +12/-0 hour						
	IR ∶ More than 12.5MΩ· <i>μ</i> F							
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage						
Resistance	Tan δ : 0.125 max	Max. operating temperature						
	IR : More than 25MΩ· <i>μ</i> F							
		1000+48/-0 hour						
Temperature	Capacitance change : within ±7.5%	1 cycle condition						
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 °C						
		\rightarrow Max. operating temperature \rightarrow 25 °C						
		5 cycles test						

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5°C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.